

SuperQ™ 200-V N-Channel Power MOSFET

FEATURES

- Wide SOA and current capability
- Robustness under fault conditions
- 100% UIS tested in production
- Low switching losses, Q_{sw} and E_{oss}
- Easier paralleling with $\pm 0.5V$ gate threshold

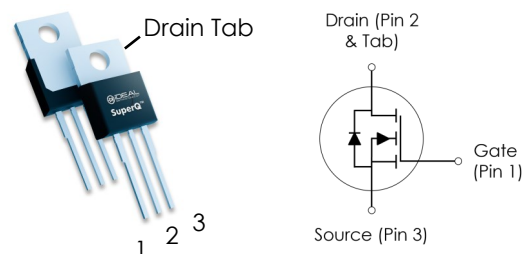
APPLICATIONS

- Motor control
- Boost converters and SMPS control FETs
- Secondary side synchronous rectifier

DESCRIPTION

Engineered for SMPS and high-efficiency motor drives, this 200V SuperQ MOSFET delivers ultra-low conduction and switching losses in a robust TO-220 package. Featuring best-in-class $R_{DS(on)}$, Q_{sw} and E_{oss} , it minimizes heat dissipation at both full and partial loads.

PRODUCT SUMMARY



TO-220

Parameter	Value	Unit
$T_A = 25^\circ C$		
V_{DS}	200	V
$R_{DS(on),max}$	25	m Ω
I_D	40	A
Q_G	26.5	nC
Q_{sw}	2.7	nC
E_{oss}	1	μJ



ORDERING INFORMATION

Part Number	Package	Marking	Packaging
iS20M028S1P	TO-220	iS20M028S1	50pc Tube

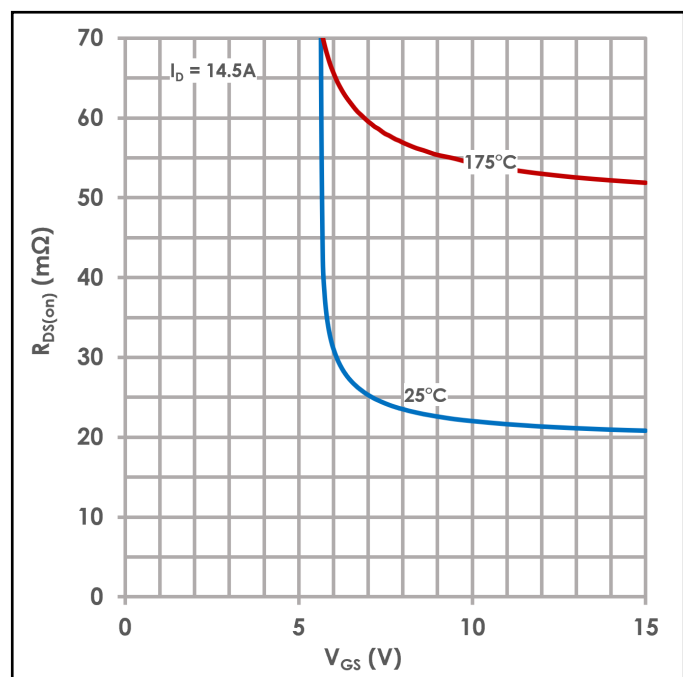


Figure 1: Typical Drain-Source On Resistance

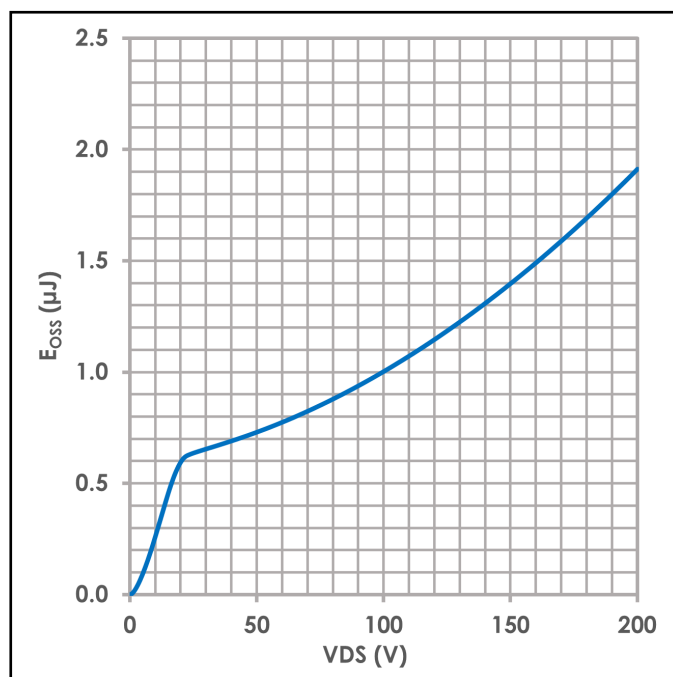


Figure 2: Typical Coss Stored Energy

ABSOLUTE MAXIMUM RATINGS

SYMBOL	PARAMETER (T _A = 25°C unless otherwise specified)	VALUE	UNIT
V _{GS}	Gate-to-source voltage	± 20	V
I _D	Continuous drain current (silicon limited), T _C = 25°C	40	A
	Continuous drain current (silicon limited), T _C = 100°C	28	
I _{DM}	Pulsed drain current	154	A
P _D	Power dissipation, T _C = 25°C	100	W
T _J , T _{stg}	Operating junction, storage temperature	-55 to 175	°C
E _{AS}	Avalanche energy, single pulse I _D = 17.8A, R _{GS} = 25Ω	159	mJ

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER (T _A = 25°C unless otherwise specified)	VALUE			UNIT
		MIN	TYP	MAX	
R _{θJC}	Junction-to-case thermal resistance - TO-220	-	-	1.5	°C/W
R _{θJA}	Junction-to-ambient thermal resistance ⁽¹⁾	-	-	40	°C/W
R _{θJA}	Junction-to-ambient thermal resistance, minimal footprint	-	-	62	°C/W

(1) 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.

ELECTRICAL CHARACTERISTICS (T _A = 25°C unless otherwise specified)						
SYMBOL	PARAMETER	TEST CONDITIONS	VALUE			UNIT
			MIN	TYP	MAX	
STATIC CHARACTERISTICS						
BV _{DSS}	Drain-to-source voltage	V _{GS} = 0V, I _D = 1mA	200	-	-	V
I _{DSS}	Drain-to-source leakage current	V _{GS} = 0V, V _{DS} = 160V, T _J = 25°C	-	0.03	1	μA
		V _{GS} = 0V, V _{DS} = 160V, T _J = 125°C ⁽²⁾	-	13	100	
I _{GSS}	Gate-to-source leakage current	V _{DS} = 0V, V _{GS} = 20V	-	0.4	100	nA
V _{GS(th)}	Gate-to-source threshold voltage	V _{DS} = V _{GS} , I _D = 70μA	3.1	3.6	4.1	V
R _{DS(on)}	Drain-to-source on-resistance	V _{GS} = 10V, I _D = 14.5A	-	22	25	mΩ
g _{fs}	Transconductance ⁽²⁾	V _{DS} = 10V, I _D = 14.5A	16	31	-	S
DYNAMIC CHARACTERISTICS						
C _{iss}	Input capacitance ⁽²⁾	V _{GS} = 0V, V _{DS} = 100V, f = 100kHz	-	1,865	2,425	pF
C _{rss}	Reverse transfer capacitance ⁽²⁾		-	12	16	
C _{oss}	Output capacitance ⁽²⁾		-	67	86	
C _{o(er)}	Effective output capacitance	V _{DS} = 0 to 100V, V _{GS} = 0V	-	197	-	
R _G	Series gate resistance	f = 1MHz	-	4.5	6.8	Ω
t _{d(on)}	Turn-on delay time	V _{DS} = 100V, V _{GS} = 10V, I _{DS} = 14.5A, R _{G,EXT} = 0 Ω	-	8.5	-	ns
t _r	Rise time		-	1.9	-	
t _{d(off)}	Turn-off delay time		-	24.7	-	
t _f	Fall time		-	11.3	-	
GATE CHARGE CHARACTERISTICS						
Q _g	Gate charge total ⁽²⁾	V _{DS} = 100V, I _D = 14.5A, V _{GS} = 0 to 10V	-	26.5	34	nC
Q _{sw}	Switching charge ⁽³⁾		-	2.7	-	
Q _{gd}	Gate to drain charge ⁽²⁾		-	1.4	1.8	
V _{plateau}	Gate plateau voltage		-	5.7	-	V
Q _{oss}	Output charge ⁽²⁾	V _{DS} = 0 to 100V, V _{GS} = 0V	-	95	108	nC
E _{oss}	Capacitive stored energy		-	1	-	μJ
DIODE CHARACTERISTICS						
V _{SD}	Diode forward voltage	I _{SD} = 14.5A, V _{GS} = 0V	-	1.0	1.2	V
Q _{rr}	Reverse recovery charge	V _{DS} = 100V, I _F = 14.5A,	-	425	-	nC
t _{rr}	Reverse recovery time	di/dt = 100A/μs	-	107	-	ns

(2) Defined by design. Not subject to production test.

(3) Q_{sw} should be used for switching loss calculations. See Figure 16 and Q_{sw} application note on www.idealsemi.com

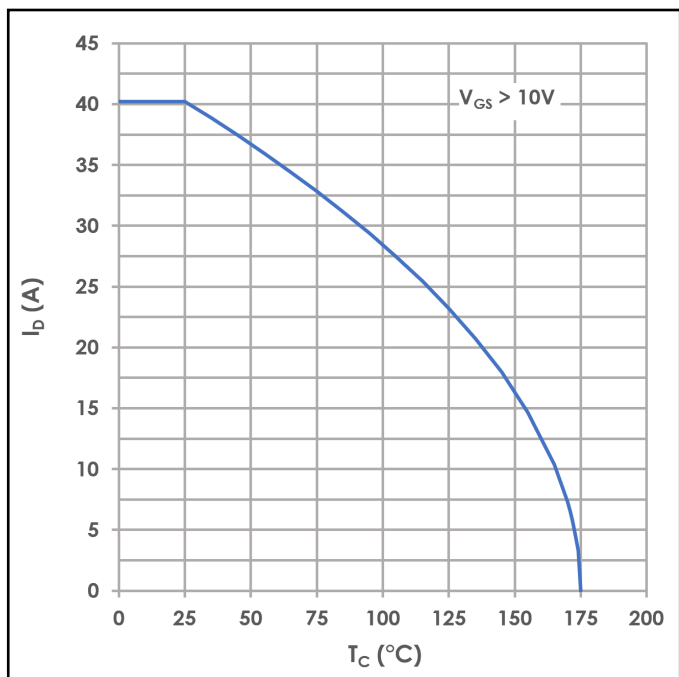


Figure 3: Drain Current

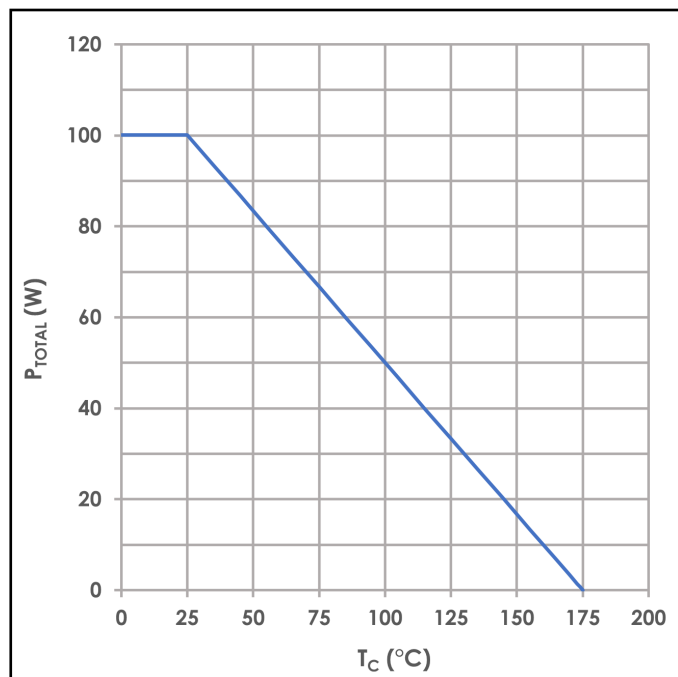


Figure 4: Power Dissipation

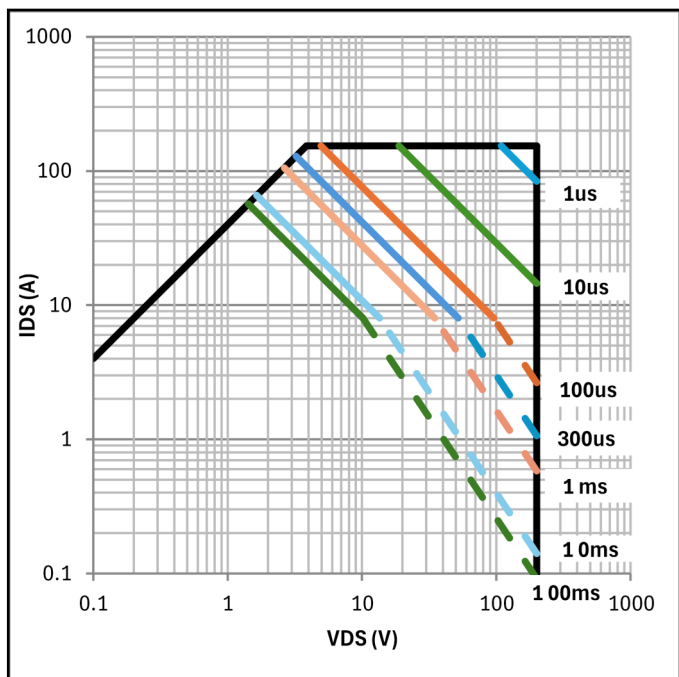


Figure 5: Safe Operating Area

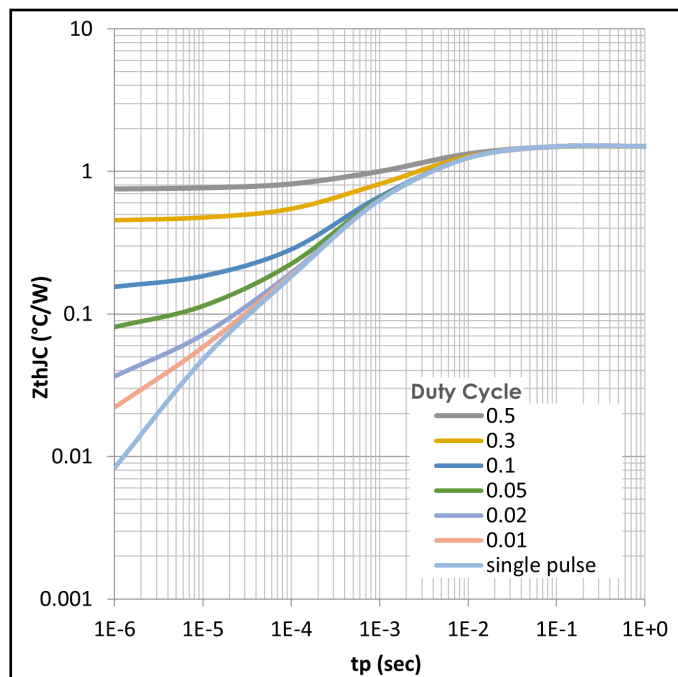


Figure 6: Max Transient Thermal Impedance

Ratings and Characteristics Curves

($T_A = 25^\circ\text{C}$ unless otherwise specified)

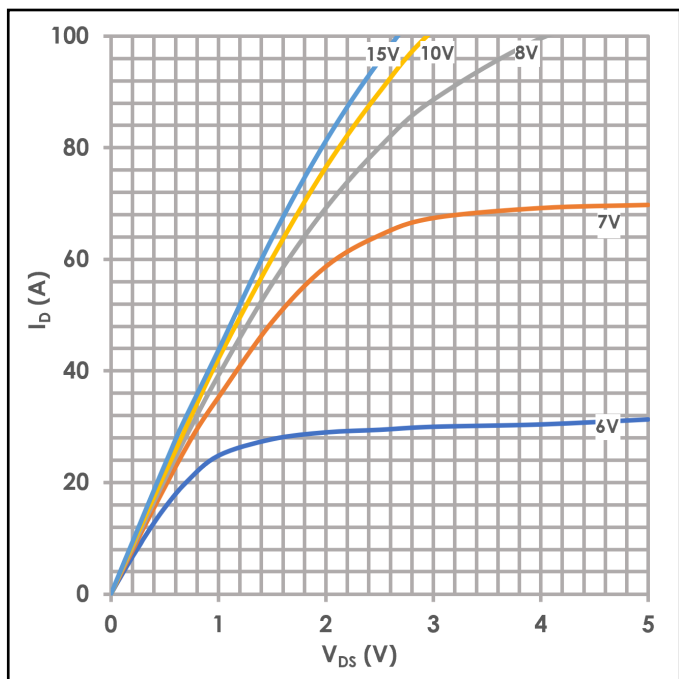


Figure 7: Typical Output Characteristics

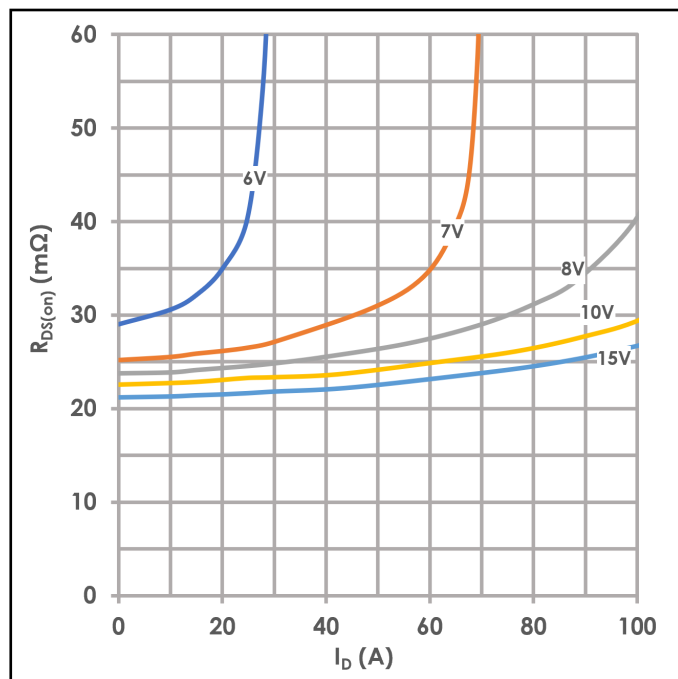


Figure 8: Typical Drain-Source On-Resistance

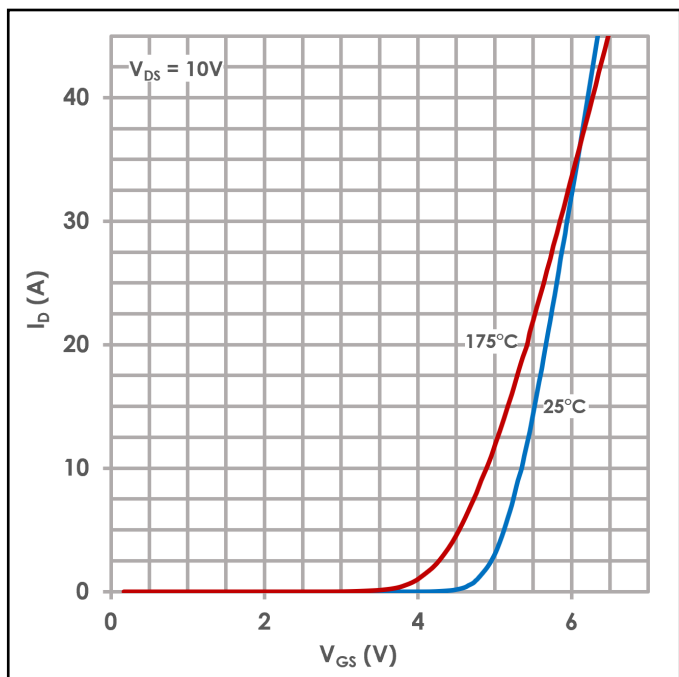


Figure 9: Typical Transfer Characteristics

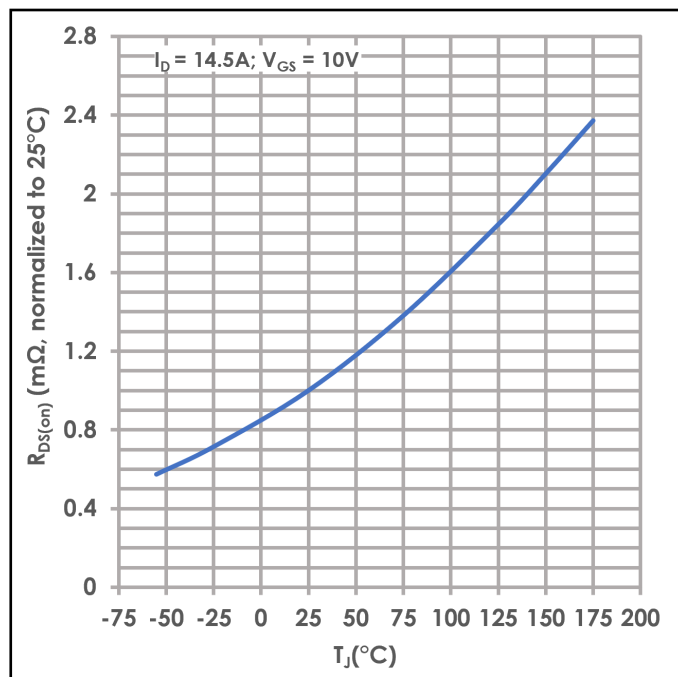


Figure 10: Normalized On-State Resistance vs. Temperature

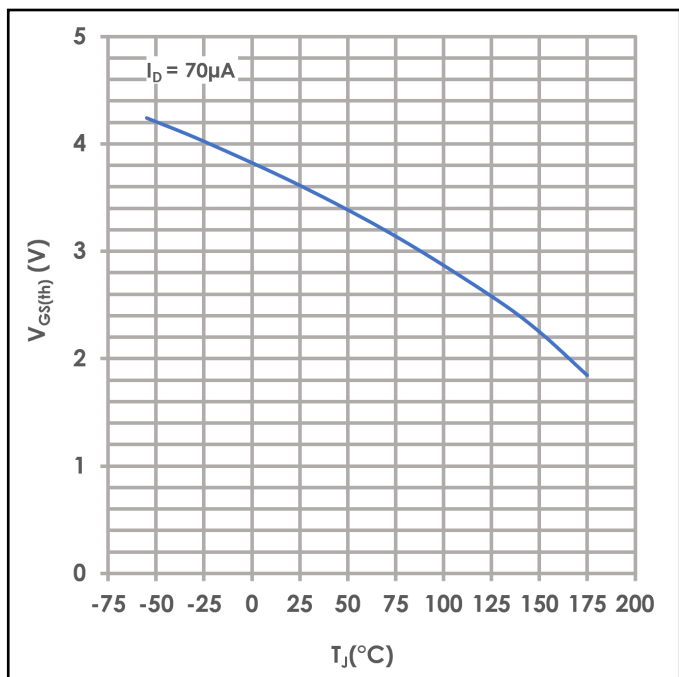


Figure 11: Typical Threshold Voltage

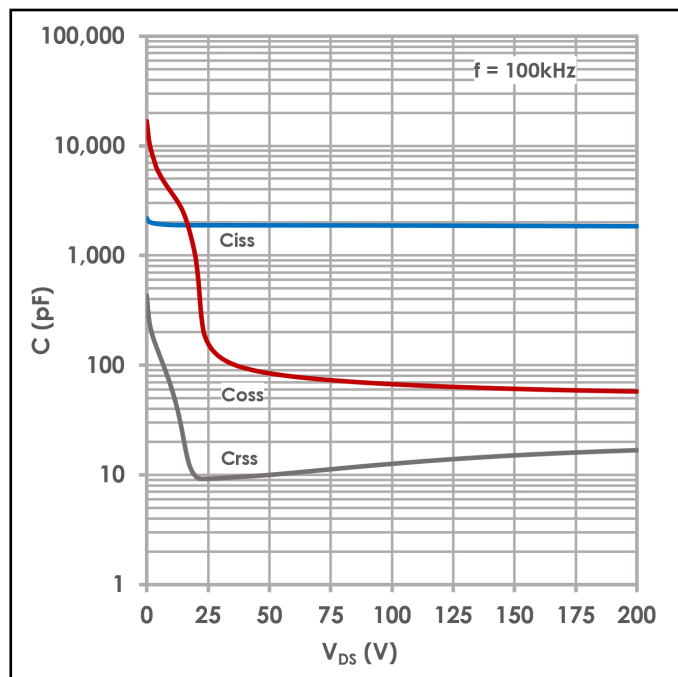


Figure 12: Typical Capacitances

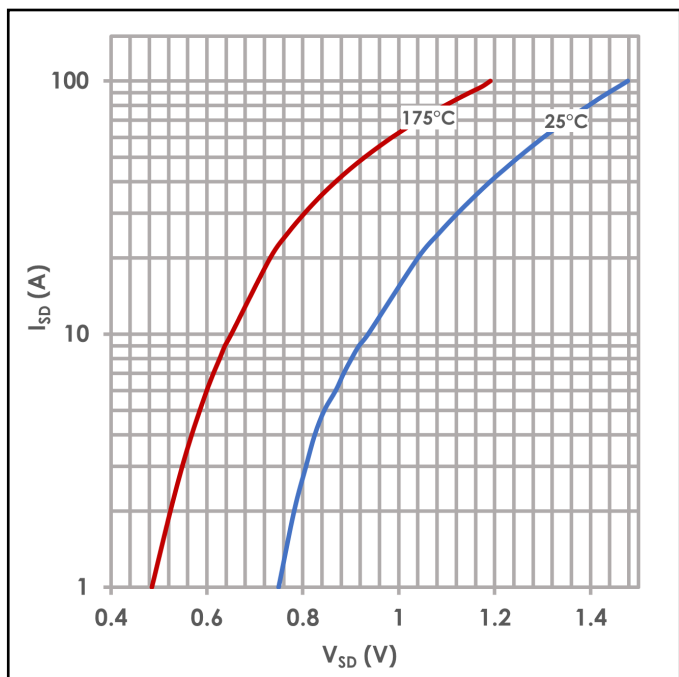


Figure 13: Typical Diode Forward Voltage

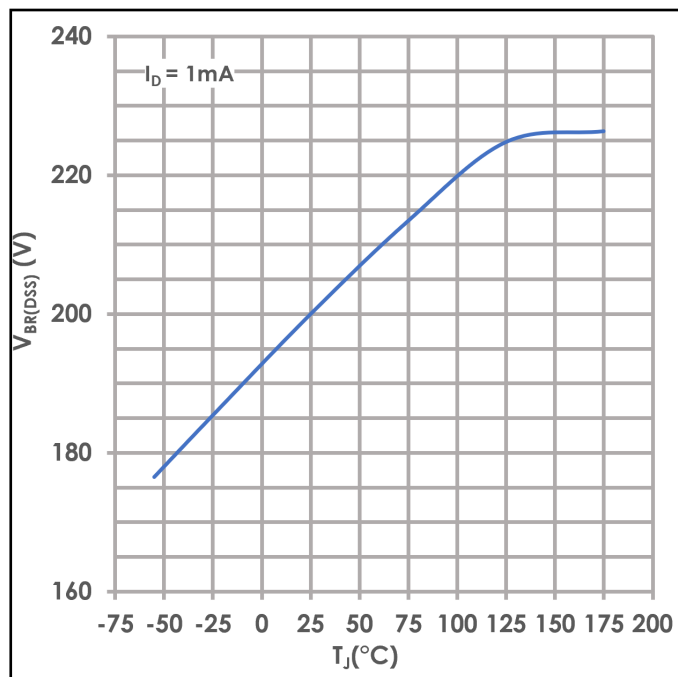


Figure 14: Min Drain-Source Breakdown Voltage

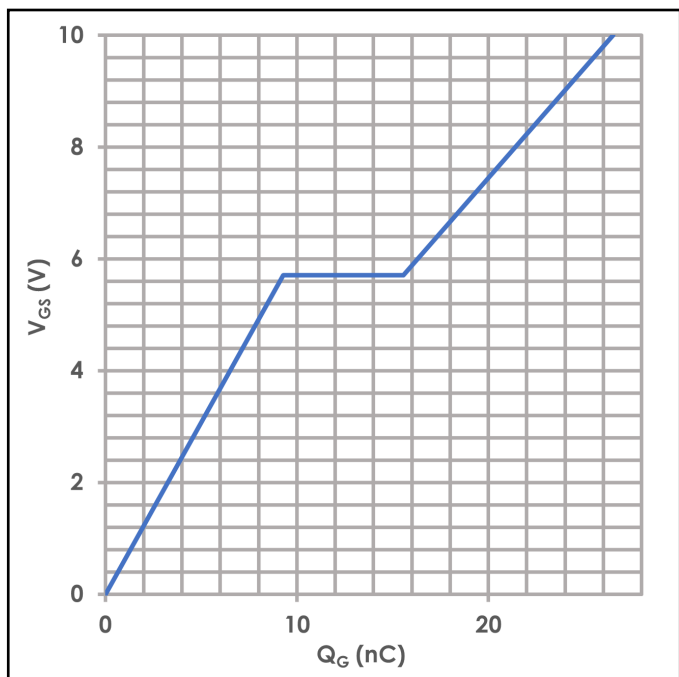


Figure 15: Typical Gate Charge

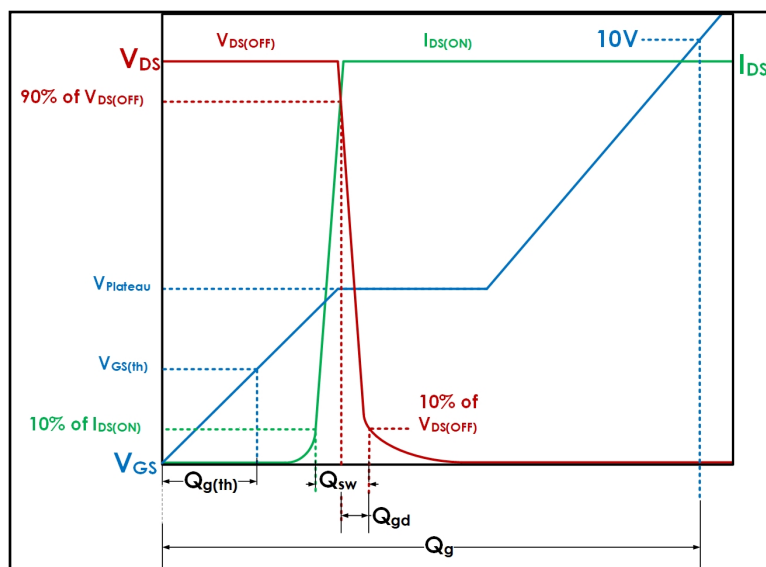
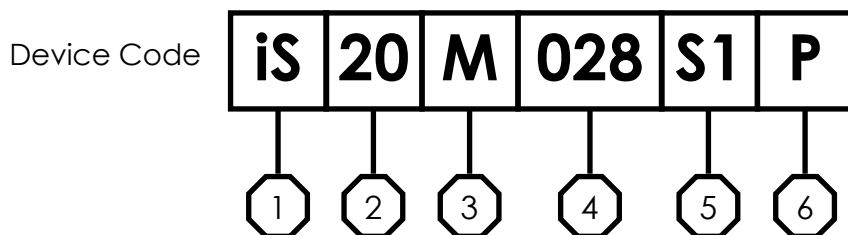


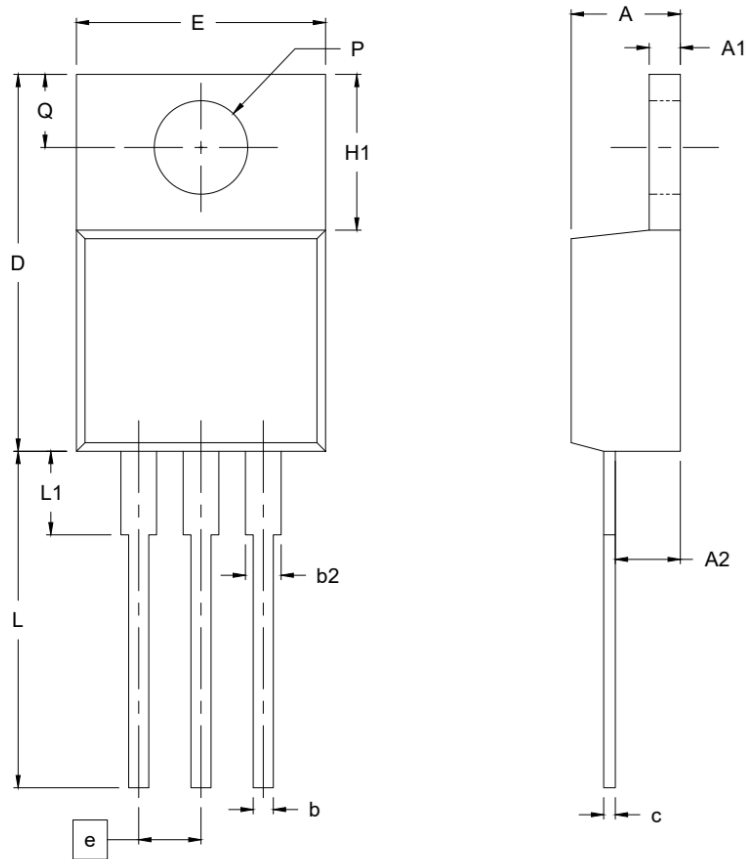
Figure 16: Gate Charge Definitions

DEVICE DECODER RING



-  — iDEAL Semiconductor product
-  — Voltage rating divided by 10 (200V)
-  — M = N-Channel MOSFET, Standard Threshold
-  — Maximum drain-to-source resistance
-  — SuperQ™ Generation
-  — P = TO-220

TO-220 Package Drawing



SYMBOL	MIN	MAX
A	4.19	4.82
A1	1.14	1.40
A2	2.38	2.92
b	0.63	1.01
b2	1.13	1.78
c	0.31	0.64
D	14.22	16.51
E	9.66	10.66
e	2.54 BSC	
H1	5.85	6.85
L	12.70	14.73
L1	2.39	4.42
P	3.54	4.08
Q	2.54	3.42

Notes:

1. All linear dimensions in millimeters
2. Dimensions D and E do not include mold flash or protrusions

Revision History		
Version	Date	Comments
1.0	July 2025	Initial Release
1.1	September 2025	Gate charge characteristics table updated. Figure 16 added

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